SNN1055HSLV
Form-In-Place


*does not represent actual color

SNN1055HSLV

A Silver/Nickel filled heat curable silicone Form-In-Place grade.

Laird introduces another product in the EMI Sentry family SNN1055HSLV is a Silver/Nickel filled silicone paste which can achieve ultra-small bead dimension during dispensing process. It also has good shielding performance with balance mechanical properties.

SNN1055HSLV is specially fit for precision electronic modules in which space is condensed and have high shielding requirement.

Laird's Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

TYPICAL VALUES

	TEST METHOD	UNITS	SNN1055HSLV
Elastomer			Silicone
Filler Type			Silver/Nickel
ELECTRICAL PROPERTIES			
Volume Resistivity	WI-QA-4153	ohm-cm	>0.01
Shielding Effectiveness, 300 MHz to 40 GHz	MIL-DTL-83528C, Cavity to cavity	dB	90(avg.)
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	55
Density (uncured)	Helium Pycnometer	g/cm^3	3.0
(cured)	ASTM D792	g/cm^3	3.6
Compression Set	ASTM D395 125°C, 22hrs	%	20
Adhesion Strength	WI-QA-4152 to Aluminum surface	N/cm^2	>180
Temperature Range		°C	-55 to 125
UL Flammability Rating	UL94 (between Al)		V0
Outgassing	ASTM E595		
Total Mass Loss (TML<1%)			0.16%
Collected Volatile Condensable Material (CVCM<0.1%)			0.04%
CURING REQUIREMENTS			
Curing Conditions			100°C Min.
Full Cure(a)			2 hours
STORAGE REQUIREMENTS			
Storage Temperature		°C	-20±10
Shelf Life			6 months

(a)Time to effectively cure a bead will necessarily depend on individual conditions, including but not limited to bead size, shield size and weight, oven capacity, and oven amp-rates.

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